

Chairs R. Ambat / H. Schweigart

11:00	O-7822	Perspectives on the climatic reliability issues of electronic devices <u>R. Ambat</u> , TU of Denmark, Kgs. Lyngby/DK
11:20	O-7819	Brief introduction to the mechanism of electrochemical migration <u>H. Schweigart</u> , Zestron Europe, Ingolstadt/D
11:40	O-7818	Influence of the printed circuit board design on electrochemical migration and surface insulation <u>M. Nowotnick</u> , Universität Rostock/D; S. Mattern, Robert Bosch GmbH, Stuttgart/D
12:00	O-7447	Electrochemical migration in electronics: effect of contamination and bias conditions <u>V. Verdingovas</u> , M.S. Jellesen, O-R. Ambat, TU of Denmark, Lyngby/DK
12:20	O-7082	Contamination profile of printed circuit board assemblies in relation to soldering types and conformal coating <u>H. Conseil</u> , M.S. Jellesen, R. Ambat, Technical University of Denmark, Lyngby/DK

12:40 Lunch

Chairs R. Ambat / H. Schweigart

14:00	O-7495	Corrosion reliability of electronics: the influence of solder temperature on the decomposition of flux activators <u>K. Piotrowska</u> , H. Conseil, M.S. Jellesen, R. Ambat, TU of Denmark, Lyngby/DK
14:20	O-7227	Cleaning in electronics: understanding Today's needs <u>J. Cetier</u> , P.J. Duchi, Inventec, Yverdon Les Bains/CH; A.M. Laugt, Inventec, Vincennes/F
14:40	O-7225	Solder paste residue corrosivity assessment: Bono test <u>J. Cetier</u> , C. Puechagut, A.M. Laugt, E. Guene, R. Anisko, Inventec, Vincennes/F
15:00	O-7426	Corrosion in electronics: overview of failures and countermeasures <u>M.S. Jellesen</u> , V. Verdingovas, H. Conseil, R. Ambat, TU of Denmark, Lyngby/DK
15:20	O-7521	Salt spray corrosion test methods - an overview A.B. Kentved, <u>K.A. Schmidt</u> , DELTA, Danish Electronics, Light & Acoustics, Hoersholm/DK

15:40 Coffee break

Chairs R. Ambat / H. Schweigart

16:10	O-7203	An on-site atmospheric-corrosion sensor <u>R. Minamitani</u> , Hitachi Ltd., Ibaraki/J
16:30	O-7824	Environmental stress corrosion of polybutylenterephthalate: a common material for electronic housings G. Klett, M. Fürtsch, A. Hachtel, <u>L. Müller</u> , Robert Bosch GmbH, Reutlingen/D
16:50	O-7236	The effect of a post-electroplating electrochemical oxidation treatment on whisker formation from tin coatings <u>M.A. Ashworth</u> , D. Haspel, L. Wu, G.D. Wilcox, R.J. Mortimer, Loughborough University/UK
17:10	O-7403	Tin electrodeposits produced using non-aqueous ionic liquid electrolytes: whisker formation <u>C.J. Stuttle</u> , M.A. Ashworth, G.D. Wilcox, R.J. Mortimer, Loughborough University/UK
17:30	O-7823	Basic physics of moisture challenges in electronic packaging - a tutorial overview <u>J. Jacobsen</u> , A. Holm, J.P. Krog, L. Rimestad, A. Riis, Grundfos A/S, Bjerringbro/DK